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August 2015

FCPF850N80Z

N-Channel SuperFET® II MOSFET

800 V, 8 A, 850 mΩ

Features

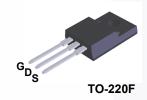
- Typ. $R_{DS(on)} = 710 \text{ m}\Omega \text{ (Typ.)}$
- Ultra Low Gate Charge (Typ. Q_g = 22 nC)
- Low E_{oss} (Typ. 2.3 uJ @ 400V)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 106 pF)
- · 100% Avalanche Tested
- · RoHS Compliant
- · ESD Improved Capability

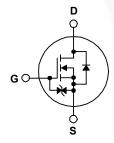
Applications

- AC DC Power Supply
- · LED Lighting

Description

SuperFET® II MOSFET is Fairchild Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. In addition, internal gate-source ESD diode allows to withstand over 2kV HBM surge stress. Consequently, SuperFET II MOSFET is very suitable for the switching power applications such as Audio, Laptop adapter, Lighting, ATX power and industrial power applications.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

| Symbol | | Parameter | | FCPF850N80Z | Unit | |
|-----------------------------------|--|---------------------------------------|---------------------------------------|-------------|------|--|
| V _{DSS} | Drain to Source Voltage | | | 800 | V | |
| V _{GSS} | Cata ta Cauraa Valtaga | - DC | | ±20 | V | |
| | Gate to Source Voltage | - AC | (f > 1 Hz) | ±30 | V | |
| I _D | Drain Current | - Continuous (T _C = 25°C) | | 8.0* | _ | |
| | Diam Current | - Continuous (T _C = 100°C) | - Continuous (T _C = 100°C) | | Α | |
| I _{DM} | Drain Current | - Pulsed | (Note 1) | 18* | Α | |
| E _{AS} | Single Pulsed Avalanche Energ | у | (Note 2) | 114 | mJ | |
| I _{AR} | Avalanche Current | | (Note 1) | 1.2 | Α | |
| E _{AR} | Repetitive Avalanche Energy | | (Note 1) | 0.284 | mJ | |
| dv/dt | MOSFET dv/dt | | | 100 | 1// | |
| αν/αι | Peak Diode Recovery dv/dt | | (Note 3) | 20 | V/ns | |
| D | Dawer Dissipation | (T _C = 25°C) | | 28.4 | W | |
| P_{D} | Power Dissipation - Derate Above 25°C | | | 0.24 | W/°C | |
| T _J , T _{STG} | Operating and Storage Tempera | ature Range | | -55 to +150 | °C | |
| TL | Maximum Lead Temperature for | r Soldering, 1/8" from Case for 5 Se | conds | 300 | °C | |

^{*}Drain current limited by maximum junction temperature, with heatsink.

Thermal Characteristics

| Symbol | Parameter | FCPF850N80Z | Unit |
|-----------------|---|-------------|-------|
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case, Max. | 4.4 | °C/W |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient, Max. | 62.5 | *C/VV |

Package Marking and Ordering Information

| Part Number | Top Mark | Package | Packing Method | Reel Size | Tape Width | Quantity |
|-------------|-------------|---------|----------------|-----------|------------|----------|
| FCPF850N80Z | FCPF850N80Z | TO-220F | Tube | N/A | N/A | 50 units |

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Unit |
|---|---|---|------|------|------|------|
| Off Charac | cteristics | | | | | |
| BV _{DSS} | Drain to Source Breakdown Voltage | $V_{GS} = 0 \text{ V, I}_{D} = 1 \text{ mA, T}_{J} = 25^{\circ}\text{C}$ | 800 | - | - | V |
| ΔBV _{DSS} / ΔT _J | Breakdown Voltage Temperature Coefficient | I _D = 1 mA, Referenced to 25°C | - | 0.8 | - | V/°C |
| I | Zero Gate Voltage Drain Current | V _{DS} = 800 V, V _{GS} = 0 V | - | - | 25 | μА |
| I _{DSS} | | $V_{DS} = 640 \text{ V}, V_{GS} = 0 \text{ V}, T_{C} = 125^{\circ}\text{C}$ | - | - | 250 | μΑ |
| I _{GSS} | Gate to Body Leakage Current | $V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$ | - | - | ±10 | μΑ |

On Characteristics

| V _{GS(th)} | Gate Threshold Voltage | $V_{GS} = V_{DS}$, $I_D = 0.6$ mA | 2.5 | - | 4.5 | V |
|---------------------|--------------------------------------|--|-----|-----|-----|----|
| R _{DS(on)} | Static Drain to Source On Resistance | $V_{GS} = 10 \text{ V}, I_D = 3 \text{ A}$ | 1 | 710 | 850 | mΩ |
| 9 _{FS} | Forward Transconductance | $V_{DS} = 20 \text{ V}, I_{D} = 3 \text{ A}$ | - | 3.5 | - | S |

Dynamic Characteristics

| C _{iss} | Input Capacitance | V 400 V V 0 V | - | 990 | 1315 | pF |
|------------------------|-------------------------------|---|---|------|------|----|
| C _{oss} | Output Capacitance | V _{DS} = 100 V, V _{GS} = 0 V, f = 1 MHz | - | 28 | 37 | pF |
| C _{rss} | Reverse Transfer Capacitance | - 1 - 1 WII 12 | - | 0.74 | - | pF |
| C _{oss} | Output Capacitance | $V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | - | 15 | - | pF |
| C _{oss(eff.)} | Effective Output Capacitance | $V_{DS} = 0 \text{ V to } 480 \text{ V}, V_{GS} = 0 \text{ V}$ | - | 106 | - | pF |
| Q _{g(tot)} | Total Gate Charge at 10V | V _{DS} = 640 V, I _D = 6 A, | - | 22 | 29 | nC |
| Q _{gs} | Gate to Source Gate Charge | V _{GS} = 10 V | - | 5 | - | nC |
| Q _{gd} | Gate to Drain "Miller" Charge | (Note 4) | - | 8.6 | - | nC |
| ESR | Equivalent Series Resistance | f = 1 MHz | - | 2.4 | - | Ω |

Switching Characteristics

| $t_{d(on)}$ | Turn-On Delay Time | | - | 16 | 42 | ns |
|---------------------|---------------------|--|-----|-----|----|----|
| t _r | Turn-On Rise Time | $V_{DD} = 400 \text{ V}, I_D = 6 \text{ A},$ | - / | 10 | 30 | ns |
| t _{d(off)} | Turn-Off Delay Time | $V_{GS} = 10 \text{ V}, R_g = 4.7 \Omega$ | -/ | 40 | 90 | ns |
| t _f | Turn-Off Fall Time | (Note 4) | - | 4.5 | 19 | ns |

Drain-Source Diode Characteristics

| Is | Maximum Continuous Drain to Source Diode Forward Current | | - | 8 | Α |
|-----------------|--|---|-----|-----|----|
| I _{SM} | Maximum Pulsed Drain to Source Diode Forward Current | - | - | 18 | Α |
| V_{SD} | Drain to Source Diode Forward Voltage V _{GS} = 0 V, I _{SD} = 6 A | - | - | 1.2 | V |
| t _{rr} | Reverse Recovery Time $V_{GS} = 0 \text{ V}, I_{SD} = 6 \text{ A},$ | - | 318 | - | ns |
| Q _{rr} | Reverse Recovery Charge dI _F /dt = 100 A/μs | - | 4.5 | - | μС |

Notes:

- 1. Repetitive rating: pulse width limited by maximum junction temperature.
- 2. I $_{AS}$ = 1.2 A, V $_{DD}$ = 50 V, R $_{G}$ = 25 Ω , Starting T $_{J}$ = 25°C
- 3. $I_{SD} \le 8$ A, di/dt ≤ 200 A/ μ s, $V_{DD} \le BV_{DSS}$, Starting T_J = 25°C
- 4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

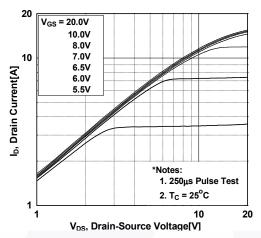


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

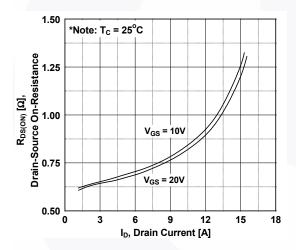


Figure 5. Capacitance Characteristics

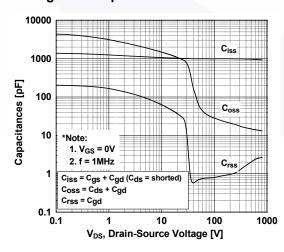


Figure 2. Transfer Characteristics

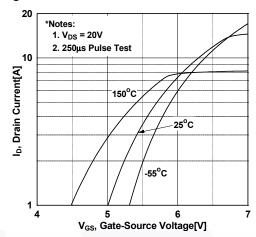


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

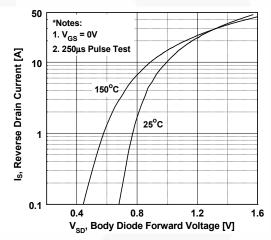
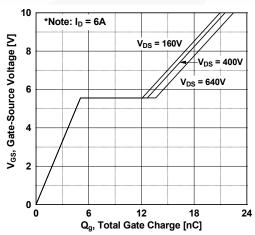


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

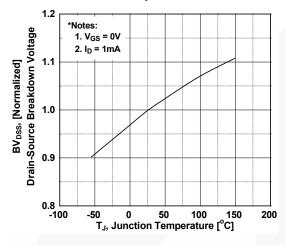


Figure 9. Maximum Safe Operating Area

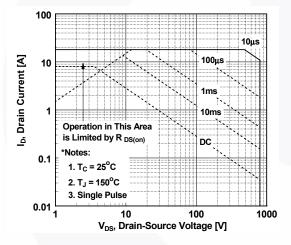


Figure 11. Eoss vs. Drain to Source Voltage

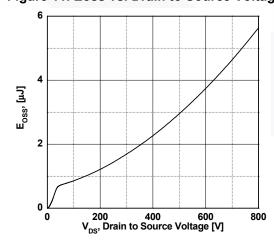


Figure 8. On-Resistance Variation vs. Temperature

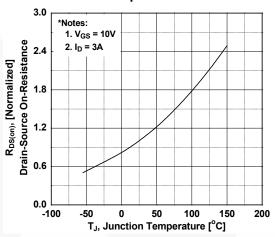
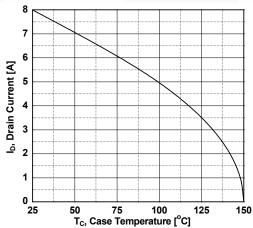
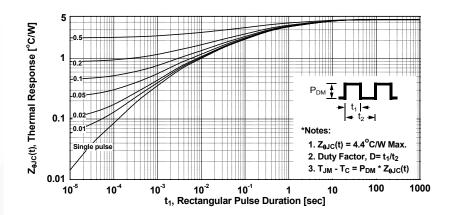


Figure 10. Maximum Drain Current vs. Case Temperature



Typical Performance Characteristics (Continued)

Figure 12. Transient Thermal Response Curve



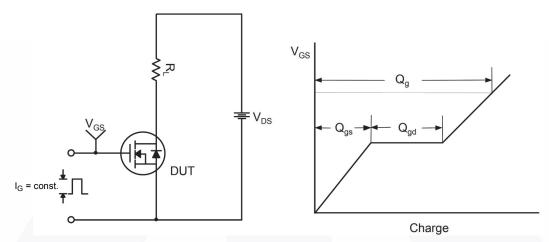


Figure 13. Gate Charge Test Circuit & Waveform



Figure 14. Resistive Switching Test Circuit & Waveforms

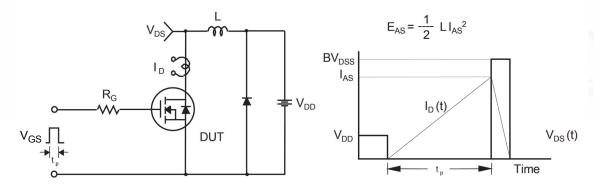


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

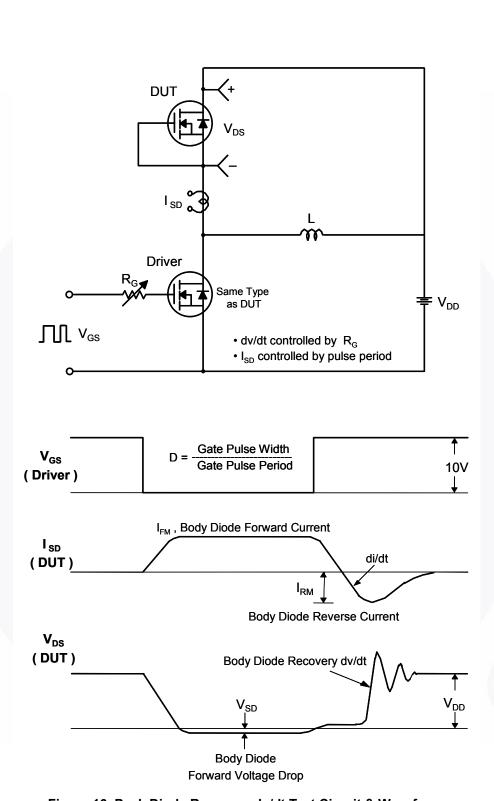
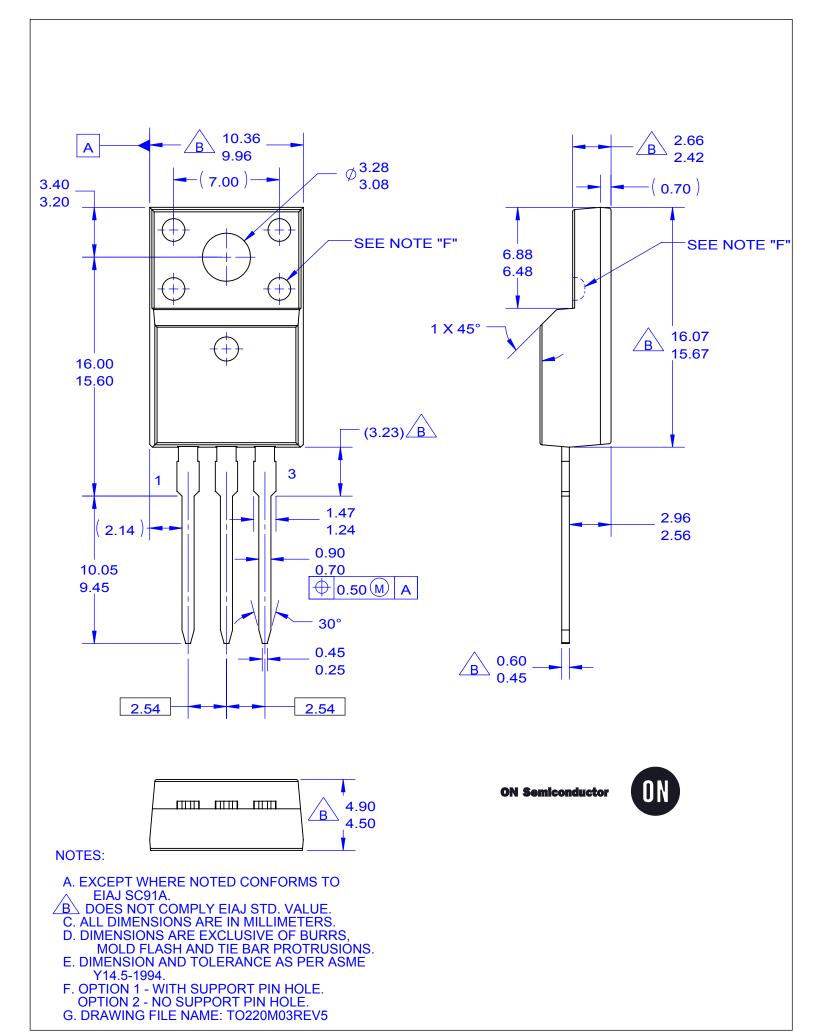


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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